PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date	
Etan G. Cohen	01/11/2013	
Sidney B. Schrum Jr.	01/15/2013	
Lawrence W. Yonge III	01/15/2013	

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated		
Street Address:	5775 Morehouse Drive		
City:	San Diego		
State/Country:	CALIFORNIA		
Postal Code:	92121		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13718399

CORRESPONDENCE DATA

Fax Number: 2817544914

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 281-758-0025

Email: jblackwell@system.foundationip.com

Correspondent Name: Andrew DeLizio
Address Line 1: 15201 Mason Road
Address Line 2: Suite 1000-312

Address Line 4: Cypress, TEXAS 77433

ATTORNEY DOCKET NUMBER:	120668	
NAME OF SUBMITTER:	Jackie Blackwell	

Total Attachments: 6

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PATENT REEL: 029697 FRAME: 0291 OF \$40.00 13/1839

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ASSIGNMENT

WHEREAS, WE,

- 1. Etan Gur COHEN, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Francisco, California,
- 2. Sidney B. SCHRUM Jr., a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive and a resident of Ocala, Florida,
- 3. Lawrence W. YONGE III, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121 and a resident of Summerfield, Florida,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to BRIDGING NETWORK DEVICES IN A HYBRID COMMUNICATION NETWORK (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/718,399 filed December 18, 2012, Qualcomm Reference No. 120668, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at <u>SAN JOSE CA</u>, on <u>JONES II 2013</u> LOCATION DATE

Etan-GUR COHEN

PATENT QUALCOMM Ref. No. 120668 Page 3 of 3

Done at _		, on		
	LOCATION		DATE	Sidney B. SCHRUM Jr.
Done at		, on		
	LOCATION		DATE	Lawrence W. YONGE III

ASSIGNMENT

WHEREAS, WE,

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- 2. Sidney B. SCHRUM Jr., a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive and a resident of Ocala, Florida,
- 3. Lawrence W. YONGE III, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121 and a resident of Summerfield, Florida,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to BRIDGING NETWORK DEVICES IN A HYBRID COMMUNICATION NETWORK (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hercinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	α.			
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	LOCATION	DATE	Etan CITR COHEN	

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QUALCOMM Ref. No. 120668

Page 3 of 3

Done at $\frac{Ocala, FL}{LOCATION}$, on $\frac{1}{15/2013}$

Sidney B. SCHRVM Jr.

Done at $\frac{O_{Cale} F_{L}}{LOCATION}$, on $\frac{1/15/200}{DATE}$

Lawrence W. YONGE III

PATENT REEL: 029697 FRAME: 0298

RECORDED: 01/25/2013